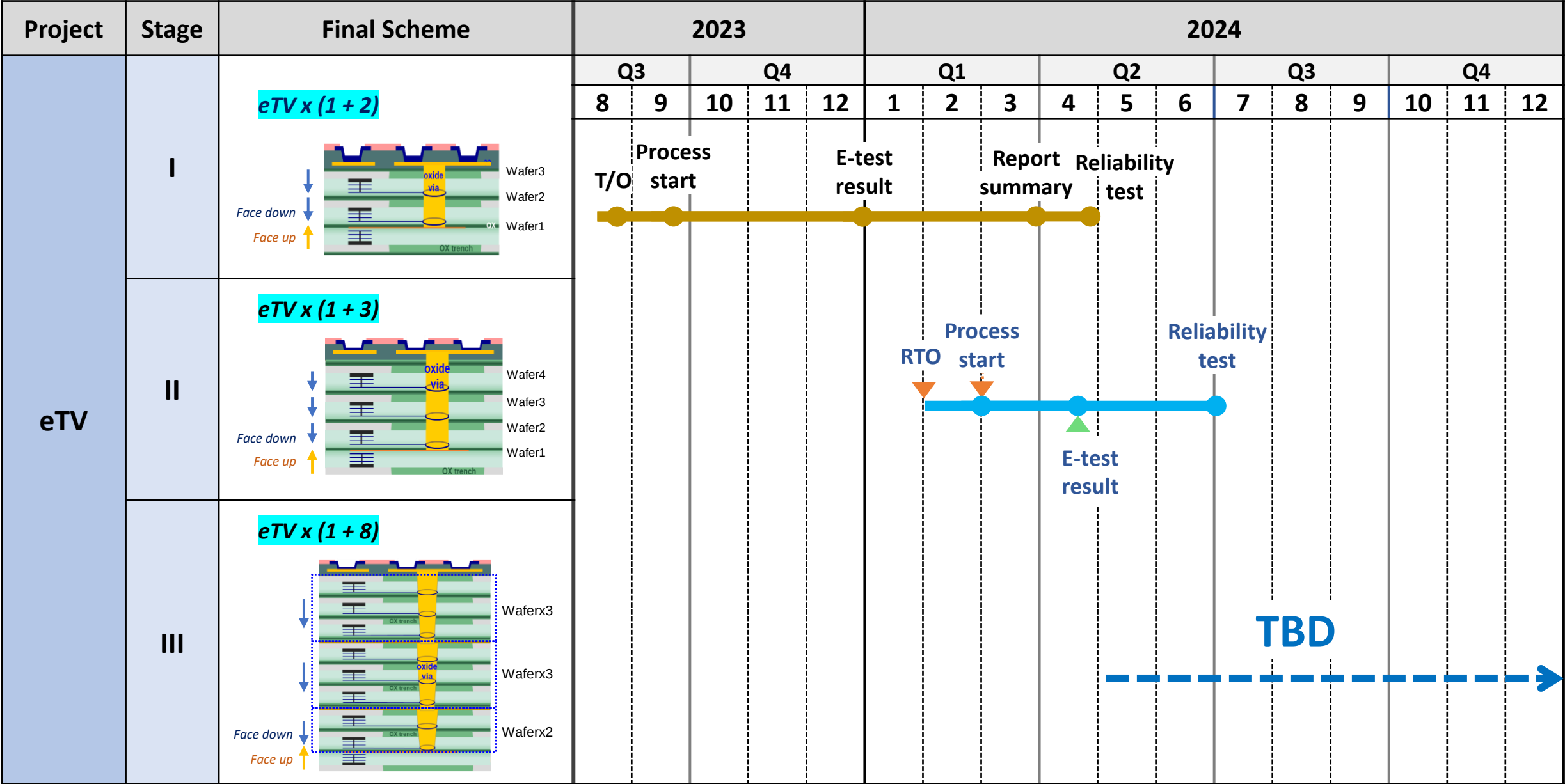


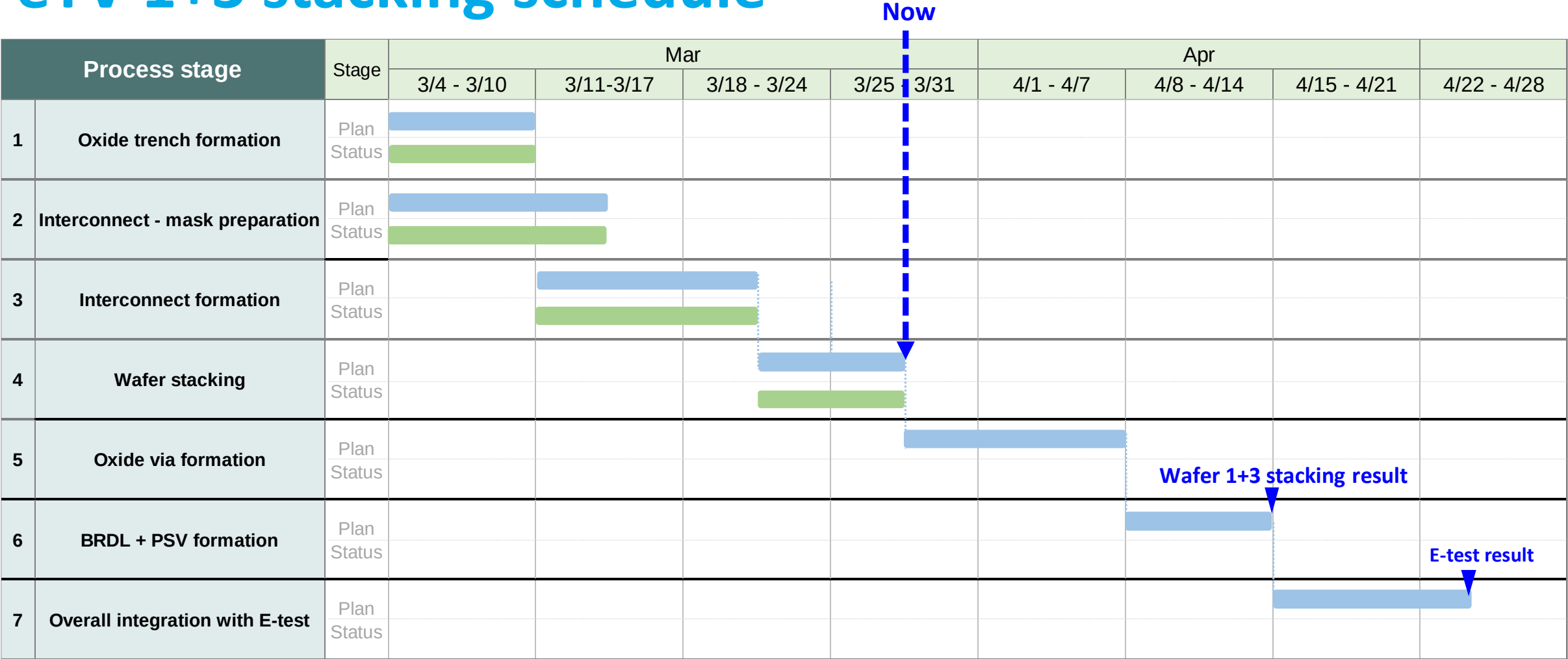
Via-In-One Project Status Update

2024/3/27

eTV master schedule



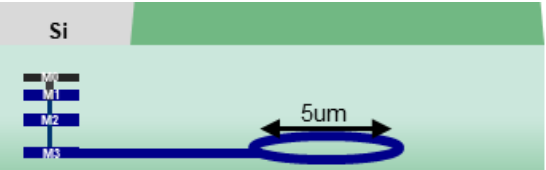
eTV 1+3 stacking schedule



- Oxide trench formation → completed without special issue.
- Interconnect formation → completed without special issue.
- Wafer stacking → on schedule, wafer stacking is ongoing.

Interconnect formation

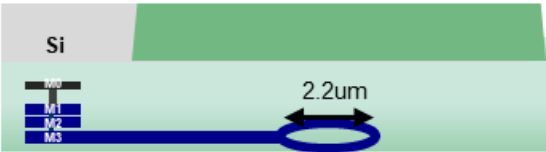
Wafer4



Wafer3



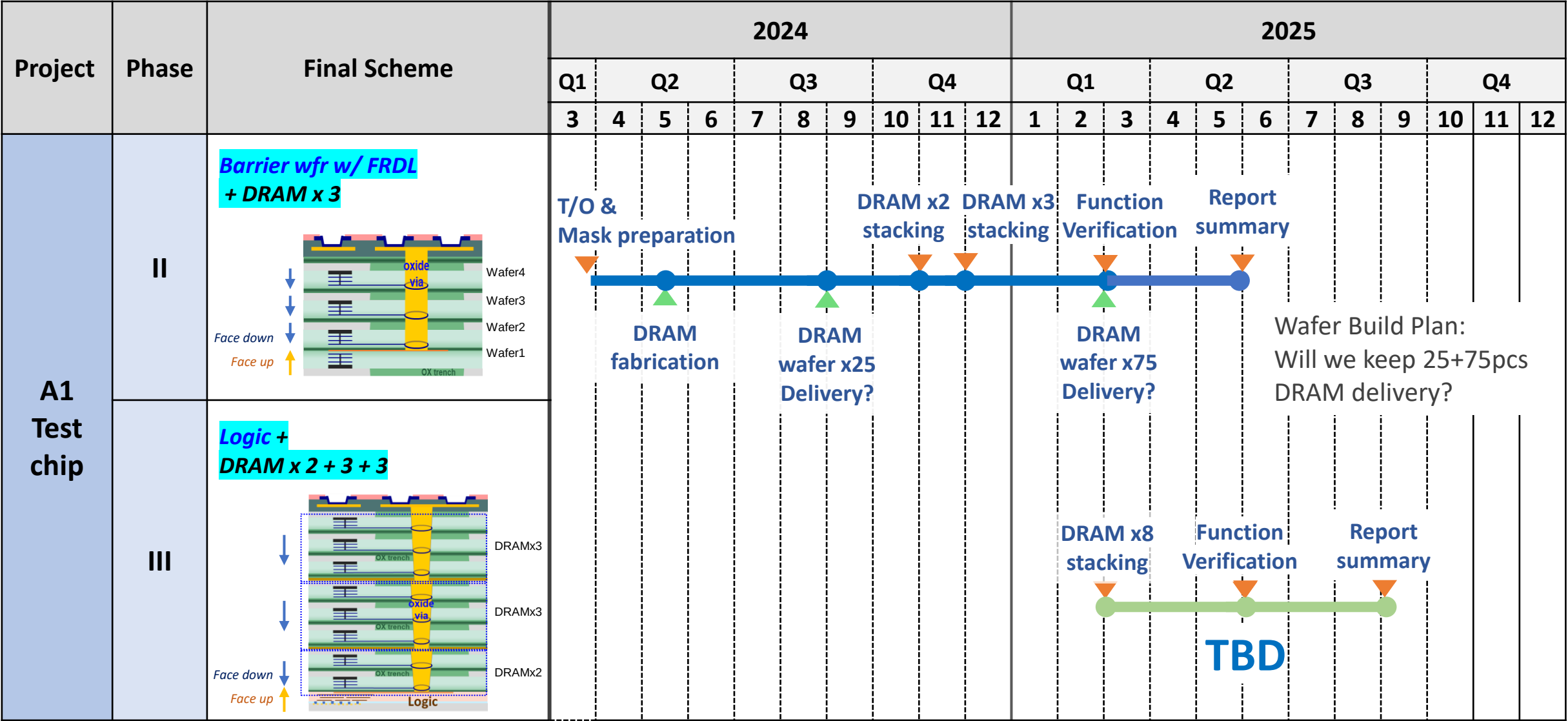
Wafer2



Layer	Stage	Spec low	Target	Spec high	CD (Mean)	Unit
Wafer4	Photo	4.50	5.00	5.50	4.809	um
	Etch	4.23	4.70	5.17	4.658	
Wafer3	Photo	3.24	3.60	3.96	3.537	
	Etch	2.97	3.30	3.63	3.272	
Wafer2	Photo	1.98	2.20	2.42	2.079	
	Etch	1.71	1.90	2.09	1.750	

- Metal ring CD show within spec on each wafer.

A1 Test-chip master schedule



Thank You